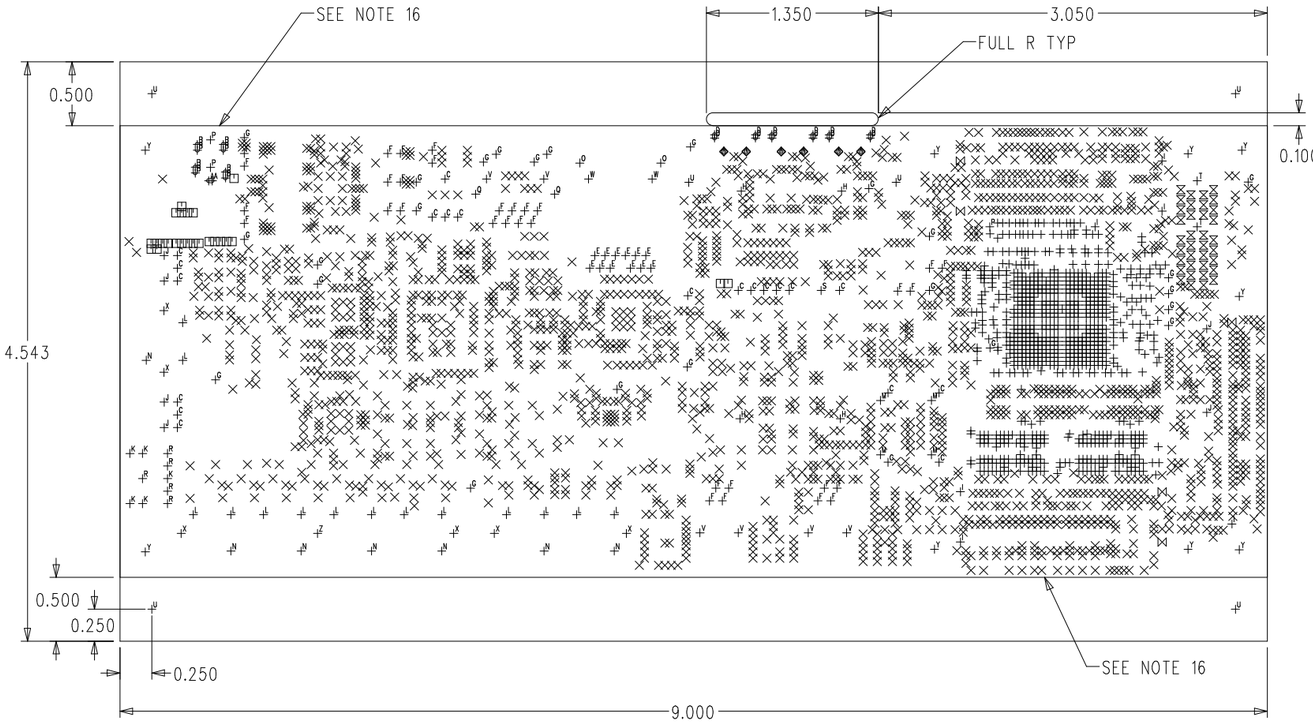
REVISIONS				
REV	DESCRIPTION OF CHANGE	DRFTR	DATE	APPROVED
0.1	NEW RELEASE	C.C.D.	07/07/14	
0.2	UPDATED PER ECO2014-069	C.C.D.	10/24/14	
1.0	UPDATED PER ECO2015-000	C.C.D.	1/16/15	
1.1	UPDATED PER ECO2015-011	C.C.D.	4/10/15	
1.2	UPDATED PER ECO2016-013	C.C.D.	3/24/16	
2.0	UPDATED PER ECO2017-013	C.C.D.	6/27/17	

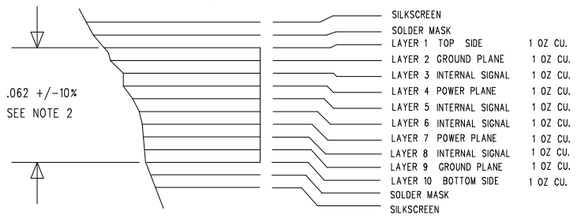
SIZE	QTY	SYM	PLATED	TOL
0.006	897	+	YES	+0.000/-0.006
0.012	2323	X	YES	+/-0.003
0.02	24	□	YES	+/-0.003
0.026 x 0.033	6	◇	YES	+/-0.003
0.028	36	⊠	YES	+/-0.003
0.028	5	⊠	NO	+/-0.003
0.032 x 0.06	1	A	YES	+/-0.003
0.032 x 0.078	4	B	YES	+/-0.003
0.033	21	C	YES	+/-0.003
0.033 x 0.059	6	D	YES	+/-0.003
0.035	12	E	YES	+/-0.003
0.038	32	F	YES	+/-0.003
0.04	24	G	YES	+/-0.003
0.04	4	H	NO	+/-0.003
0.044	6	J	NO	+/-0.003
0.045	6	K	YES	+/-0.003
0.047	5	L	NO	+/-0.003
0.051	14	M	YES	+/-0.003
0.057	4	N	NO	+/-0.003
0.059	7	P	YES	+/-0.003
0.062	2	Q	YES	+/-0.003
0.063	3	R	NO	+/-0.003
0.067	2	S	YES	+/-0.003
0.071	5	T	YES	+/-0.003
0.089	1	U	NO	+/-0.003
0.093	2	V	NO	+/-0.003
0.125	6	W	NO	+/-0.005
0.128	6	Y	NO	+/-0.005
0.138	2	AB	NO	+/-0.003
0.14	6	AC	NO	+/-0.005
0.144	9	AY	NO	+/-0.005
0.187	1	AZ	NO	+/-0.005

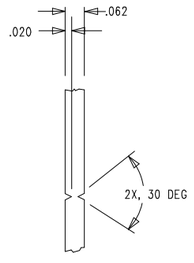


UNLESS OTHERWISE SPECIFIED

1. BOARD TO BE FABRICATED PER IPC-6012B, CLASS 2.
2. MATERIAL: FR-370HR OR EQUIVALENT. OUTER LAYERS 1 OZ/SQFT CU INNER LAYERS 1 OZ/SQFT CU FINISHED .062 +/-10%. VENDOR MAY ADJUST THICKNESS TO FULFILL NOTE 9.
3. PLATING: ADDITIONAL CU PLATING 1 OZ/SQFT ALL HOLES PLATED THROUGH, EXCEPT AS NOTED IN HOLE LEGEND. MINIMUM PTH BARREL THICKNESS = 0.0008" MINIMUM AVERAGE PER IPC-6012B WITH AMENDMENT 1, CLASS 2 REQUIREMENTS. WITH NO SINGLE MEASUREMENT LESS THAN 0.00071 IN THE PLATED HOLES.
4. FINISH: SURFACES TO BE COATED BY ENIG OF 3 TO 5 MICROINCHES OVER A MINIMUM OF 150-200 MICROINCHES OF LOW STRESS NICKEL.
5. SOLDERMASK: SOLDER MASK TO BE TRANSPARENT GREEN LPI BOTH SIDES PER GERBER FILES. VENDOR MAY ADJUST SOLDERMASK PAD SIZE AS NEEDED.
6. SILKSCREEN: WHITE EPOXY INK, APPLY TO BOTH SIDES PER GERBER FILES.
7. ARTWORK: MINIMUM FEATURE SIZE = 0.005 MINIMUM AIR GAP = 0.004
8. ALL DIMENSIONS ARE IN INCHES.
9. CONTROLLED IMPEDANCE: SEE CHART
10. NON-FUNCTIONAL COPPER THIEVING IS ALLOWED ON OPEN AREAS.
11. VIAS SHOULD BE COVERED ACCORDING TO ONE OF THE FOLLOWING METHODS. METHOD 1 IS PREFERRED.
    METHOD 1: VIAS MUST BE FILLED WITH SOLDERMASK MATERIAL AFTER ELECTROLESS NICKEL/IMMERSION GOLD AND BEFORE PRIMARY LPI MASK. AFTER THE FILL IS CURED, THE PRIMARY MASK IS THEN APPLIED WITH NO VIA APERATURES BOTH SIDES.
    METHOD 2: AFTER APPLICATION OF FULL BODY ELECTROLESS NICKEL/ IMMERSION GOLD, APPLY PRIMARY MASK WITH REDUCED VIA APERTURES THAT ARE 6 MILS LARGER THAN DRILLED HOLE DIAMETER BOTH SIDES. THEN APPLY SOLDER MASK PLUG ON COMPONENT SIDE.
12. VIA HOLES (.006 & .012) REQUIRE TANGENCY ONLY, INSTEAD OF ANNULAR RING.
13. TEARDROP PADS ARE ACCEPTABLE WHERE NEEDED.
14. REMOVAL OF NON-FUNCTIONAL PADS ON LAYERS 3, 5, 6, AND 8 IS ACCEPTABLE.
15. USE IPC-D-356A NETLIST AS SUPPLIED FOR CHECKING.
16. V SCORE 1 LINE ON BOTH SIDES OF THE BOARD. SEE DETAIL.
17. BUILD AS 1-UP PCB.

10 LAYER CONSTRUCTION DETAIL
SCALE : NONE





SCORING DETAIL
2 PLACES

LAYER	50 S/E	100 D/P WIDTH/SPACE
1 SIG	.005	.0045/.005
2 PLN		
3 SIG	.005	----------
4 PLN		
5 SIG	.0056	.0045/.010
6 SIG	.0056	.0045/.010
7 PLN		
8 SIG	.005	.0045/.010
9 PLN		
10 SIG	.005	.0045/.005

IMPEDANCE CHART
ALL IMPEDANCES +/-10%

UNLESS OTHERWISE SPECIFIED DIMENSIONS ARE IN INCHES TOLERANCES ARE : .XX +/- .010 .XXX +/- .005	CONTRACT NO.		ANALOG DEVICES 2 Elizabeth Drive Chelmsford, MA 01824
	APPROVALS	DATE	FABRICATION DRAWING ADSP-SC589 EZ-BOARD
MATERIAL SEE NOTES	DRAWN C.C.D.	6/27/17	
	CHECKED		
FINISH SEE NOTES	ENGINEERING		SIZE B DWG. NO. A0447-2013 REV. 2.0
	QUALITY		
DO NOT SCALE THIS DRAWING	MANUFACTURING		SCALE 1 : 1 SHEET 1 OF 1